

7. (Amended) The package sealing method according to claim 1, wherein the laser beam is scanned, to irradiate the bonding member point by point so that the case and the lid are welded together.

8. (Amended) The package sealing method according to claim 1, wherein the laser beam is projected through a phase hologram to generate a diffraction light pattern with which the bonding member is irradiated at a time as a whole, so that the case and the lid are welded together.

10. (Amended) The package sealing method according to claim 8, wherein the laser beam is converged by a condensing lens, the phase hologram is arranged between the condensing lens and the lid, and further, a position of the phase hologram is varied in an optical axis direction so that the diffraction light pattern can be obtained at a desired location with desired dimensions.

11. (Amended) The package sealing method according to claim 1, wherein a temperature distribution over a welding portion of the case and the lid is monitored during the laser irradiation of the bonding member.

12. (Amended) The package sealing method according to claim 1, wherein the bonding member is preheated before irradiated with the laser beam.

18. (Amended) The sealing apparatus according to claim 14, which further includes a laser scanner for scanning a laser beam to irradiate the bonding member point by point.

19. (Amended) The sealing apparatus according to claim 14, which further includes a phase hologram for forming a diffraction light pattern of the laser beam with which the bonding member is irradiated at a time as a whole.